

DATA SHEET

74F827

10-bit buffer/line driver, non-inverting
(3-State)

Product data

2004 Jan 21

Replaces Product specification 74F827/74F828 of 1994 Dec 5

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FEATURES

- High impedance NPN base inputs for reduced loading (20 μ A in HIGH and LOW states)
- I_{IL} is 20 μ A vs FAST family spec of 600 μ A
- Ideal where high speed, light bus loading and increased fan-in are required
- Controlled rise and fall times to minimize ground bounce
- Glitch free power-up in 3-State
- Flow through pinout architecture for microprocessor oriented applications
- Outputs sink 64 mA
- 74F827 is available in SSOP type II package

DESCRIPTION

The 74F827 10-Bit buffer provides high performance bus interface buffering for wide data/address paths or buses carrying parity. The device has NOR Output Enables ($\overline{OE}0$, $\overline{OE}1$) for maximum control flexibility.

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F827	6.0ns	60 mA

ORDERING INFORMATION

COMMERCIAL RANGE: $V_{CC} = 5 V \pm 10\%$; $T_{amb} = 0^{\circ}C$ to $+70^{\circ}C$

Type number	Package		
	Name	Description	Version
N74F827N	DIP24	plastic dual in-line package; 24 leads (300 mil)	SOT222-1
N74F827D	SO24	plastic small outline package; 24 leads; body width 7.5 mm	SOT137-1
N74F827DB	SSOP24	plastic shrink small outline package; 24 leads; body width 5.3 mm	SOT340-1

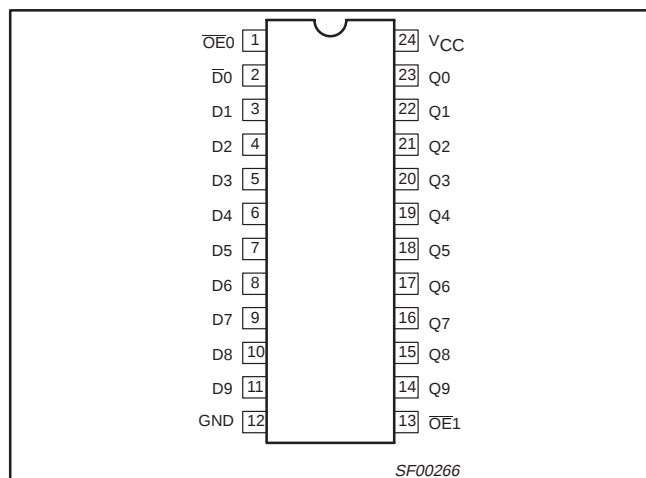
INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH / LOW
D0-D9	Data inputs	1.0/0.033	20 μ A / 20 μ A
$\overline{OE}0$ - $\overline{OE}1$	Output enable inputs (active-LOW)	1.0/0.033	20 μ A / 20 μ A
Q0-Q9	Data outputs	1200/106.7	24 mA / 64 mA

NOTES:

One (1.0) FAST Unit Load is defined as: 20 μ A in the HIGH state and 0.6 mA in the LOW state.

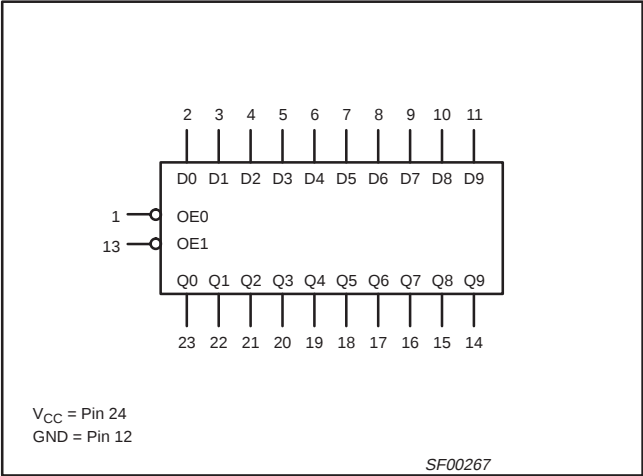
PIN CONFIGURATION



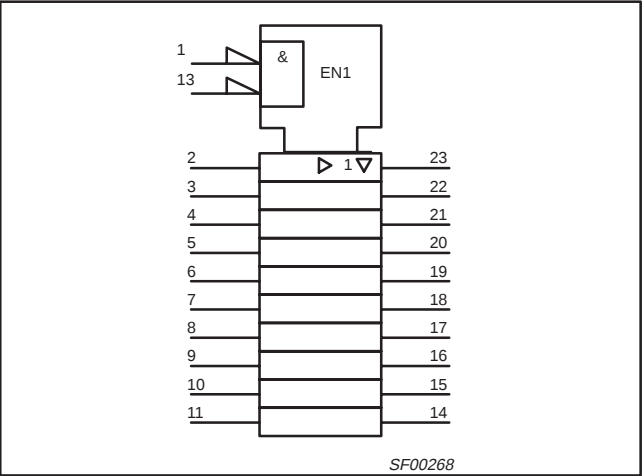
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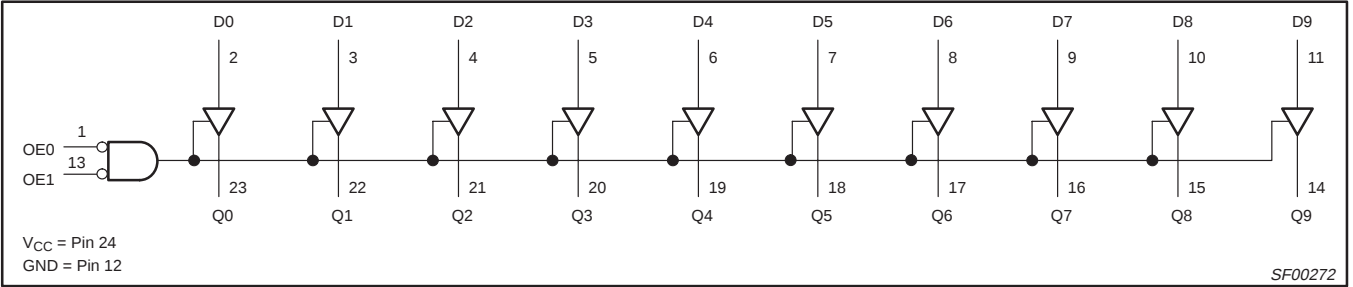
LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



LOGIC DIAGRAM



FUNCTION TABLE

INPUTS		OUTPUTS	OPERATING MODE
OE _n	D _n	Q _n	
L	L	L	Transparent
L	H	H	Transparent
H	X	Z	High impedance

H = HIGH voltage level
L = LOW voltage level
X = Don't care
Z = High impedance "off" state

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ABSOLUTE MAXIMUM RATINGS

Operation beyond the limits set forth in this table may impair the useful life of the device.
Unless otherwise noted these limits are over the operating free-air temperature range.

SYMBOL	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage	-0.5 to +7.0	V
V_{IN}	Input voltage	-0.5 to +7.0	V
I_{IN}	Input current	-30 to +5	mA
V_{OUT}	Voltage applied to output in HIGH output state	-0.5 to V_{CC}	V
I_{OUT}	Current applied to output in LOW output state	128	mA
T_{amb}	Operating free-air temperature range	0 to +70	°C
T_{stg}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS			UNIT
		Min	Nom	Max	
V_{CC}	Supply voltage	4.5	5.0	5.5	V
V_{IH}	HIGH-level input voltage	2.0	—	—	V
V_{IL}	LOW-level input voltage	—	—	0.8	V
I_{IK}	Input clamp current	—	—	-18	mA
I_{OH}	HIGH-level output current	—	—	-24	mA
I_{OL}	LOW-level output current	—	—	64	mA
T_{amb}	Operating free-air temperature range	0	—	+70	°C

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DC ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range unless otherwise noted.

SYMBOL	PARAMETER		TEST CONDITIONS ¹			LIMITS			UNIT
						MIN	TYP ²	MAX	
V _{OH}	HIGH-level output voltage		V _{CC} = MIN, V _{IL} = MAX, V _{IH} = MIN	I _{OH} = −15 mA	± 10% V _{CC}	2.4	—	—	V
					± 5% V _{CC}	2.4	3.3	—	V
			V _{CC} = MIN, V _{IL} = MAX, V _{IH} = MIN	I _{OH} = −24 mA	± 10% V _{CC}	2.0	—	—	V
					± 5% V _{CC}	2.0	—	—	V
V _{OL}	LOW-level output voltage		V _{CC} = MIN, V _{IL} = MAX, V _{IH} = MIN	I _{OL} = 64 mA	± 10% V _{CC}	—	—	0.55	V
					± 5% V _{CC}	—	0.42	0.55	V
V _{IK}	Input clamp voltage		V _{CC} = MIN; I _I = I _{IK}			—	−0.73	−1.2	V
I _I	Input current at maximum input voltage		V _{CC} = 0 V; V _I = 7.0 V			—	—	100	μA
I _{IH}	HIGH-level input current		V _{CC} = MAX; V _I = 2.7 V			—	—	20	μA
I _{IL}	LOW-level input current		V _{CC} = MAX; V _I = 0.5 V			—	—	−20	μA
I _{OZH}	Off-state output current, HIGH voltage applied		V _{CC} = MAX; V _O = 2.7 V			—	—	50	μA
I _{OZL}	Off-state output current, LOW voltage applied		V _{CC} = MAX; V _O = 0.5 V			—	—	−50	μA
I _{OS}	Short circuit output current ³		V _{CC} = MAX			−100	—	−225	mA
I _{CC}	Supply current (total)	I _{CCH}	V _{CC} = MAX			—	50	70	mA
		I _{CCL}				—	70	100	mA
		I _{CCZ}				—	60	90	mA

NOTES:

- For conditions shown as MIN or MAX, use the appropriate value specified under operating conditions for the applicable type.
- All typical values are at V_{CC} = 5 V, T_{amb} = 25 °C.
- Not more than one output should be shorted at one time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a HIGH output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

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AC CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	LIMITS					UNIT
			T _{amb} = +25 °C V _{CC} = 5 V C _L = 50 pF; R _L = 500 Ω			T _{amb} = 0 °C to +70 °C V _{CC} = 5 V ± 10% C _L = 50 pF; R _L = 500 Ω		
			Min	Typ	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation delay D _n to Q _n	Waveform 1	2.0 2.0	5.5 4.5	8.5 8.5	2.0 2.0	9.0 9.0	ns
t _{PZH} t _{PZL}	Output enable time OE _n to Q _n	Waveform 2 Waveform 3	5.0 4.0	8.0 6.0	12.0 10.5	4.5 4.0	14.0 11.5	ns
t _{PHZ} t _{PLZ}	Output disable time OE _n to Q _n	Waveform 2 Waveform 3	2.5 2.5	5.0 5.0	8.0 8.0	2.0 2.0	8.5 8.5	ns

AC CHARACTERISTICS

For 1 Output switching with $C_L = 300\text{ pF}$ and $R_L = 500\text{ }\Omega$ load

SYMBOL	PARAMETER	CONDITIONS	LIMITS					UNIT
			T _{amb} = +25 °C V _{CC} = 5 V C _L = 300 pF; R _L = 500 Ω			T _{amb} = 0 °C to +70 °C V _{CC} = 5 V ± 10% C _L = 300 pF; R _L = 500 Ω		
			MIN	Typ	Max	MIN	Max	
t _{PLH} t _{PHL}	Propagation delay D _n to Q _n	Waveform 1	— —	9.5 7.5	13.0 10.0	— —	14.0 11.0	ns
t _{PZH} t _{PZL}	Output enable time OE _n to Q _n	Waveform 2 Waveform 3	— —	15.0 9.5	20.0 13.0	— —	21.0 14.0	ns
t _{PHZ} t _{PLZ}	Output disable time OE _n to Q _n	Waveform 2 Waveform 3	— —	15.0 9.5	19.0 13.5	— —	20.0 14.0	ns

AC CHARACTERISTICS

For 10 Outputs switching with $C_L = 300\text{ pF}$ and $R_L = 500\text{ }\Omega$ load

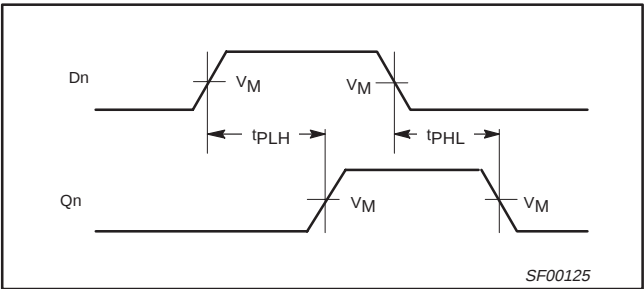
SYMBOL	PARAMETER	CONDITIONS	LIMITS					UNIT
			T _{amb} = +25 °C V _{CC} = 5 V C _L = 300 pF; R _L = 500 Ω			T _{amb} = 0 °C to +70 °C V _{CC} = 5 V ± 10% C _L = 300 pF; R _L = 500 Ω		
			MIN	Typ	Max	MIN	Max	
t _{PLH} t _{PHL}	Propagation delay D _n to Q _n	Waveform 1	—	12.0 14.0	16.0 17.0	—	17.0 18.0	ns
t _{PZH} t _{PZL}	Output enable time OE _n to Q _n	Waveform 2 Waveform 3	—	15.0 17.0	20.0 21.0	—	21.0 21.5	ns
t _{PHZ} t _{PLZ}	Output disable time OE _n to Q _n	Waveform 2 Waveform 3	—	15.0 12.5	19.0 15.5	—	20.0 16.0	ns

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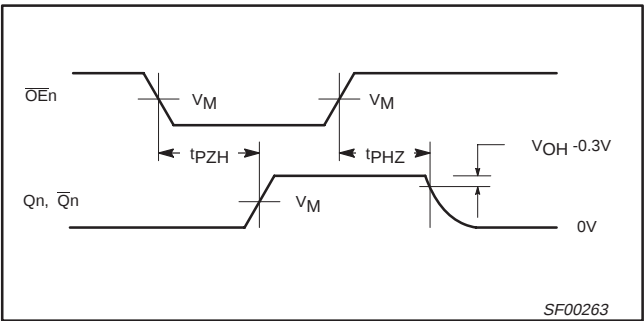
AC WAVEFORMS

For all waveforms, $V_M = 1.5 \text{ V}$



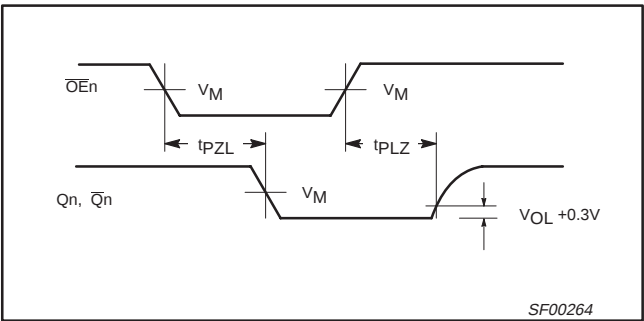
SF00125

Waveform 1. Propagation delay for non-inverting output



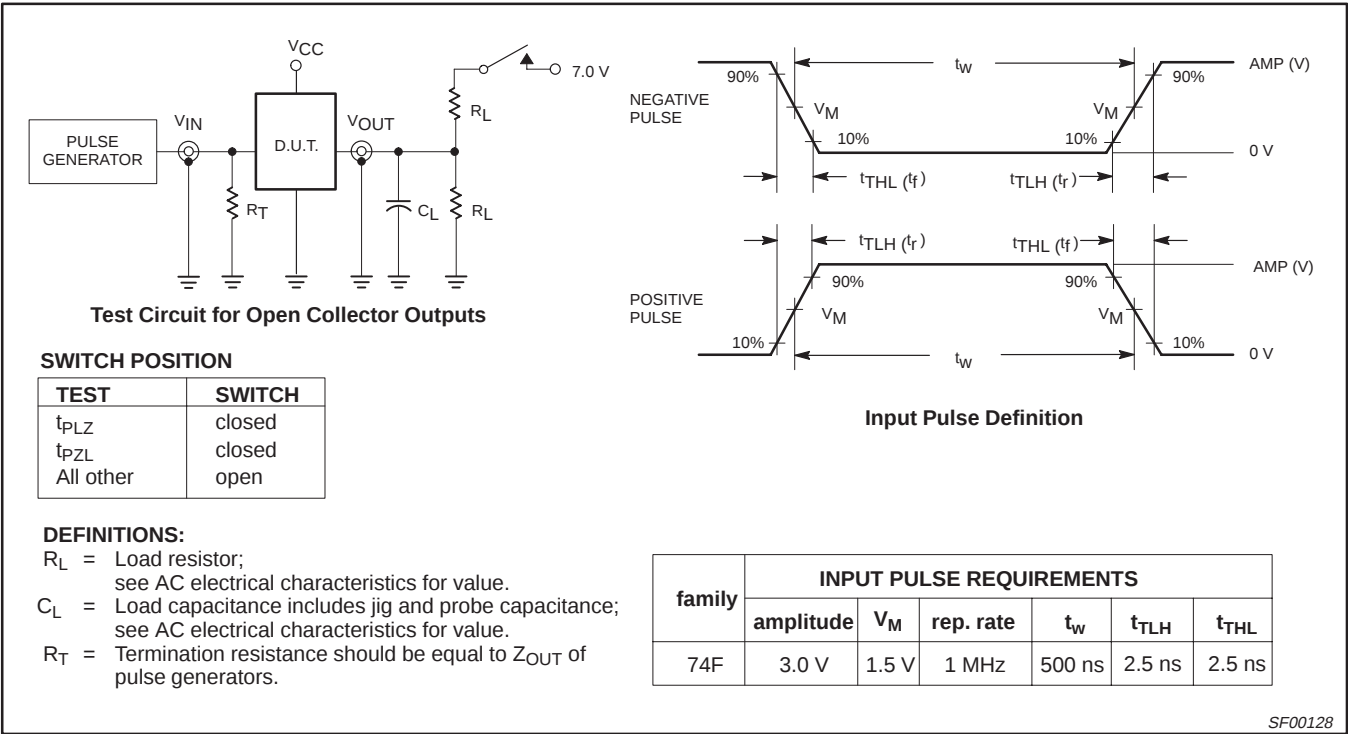
SF00263

Waveform 2. 3-State Output Enable time to HIGH level and Output Disable time from HIGH level



SF00264

Waveform 3. 3-State Output Enable time to LOW level and Output Disable time from LOW level



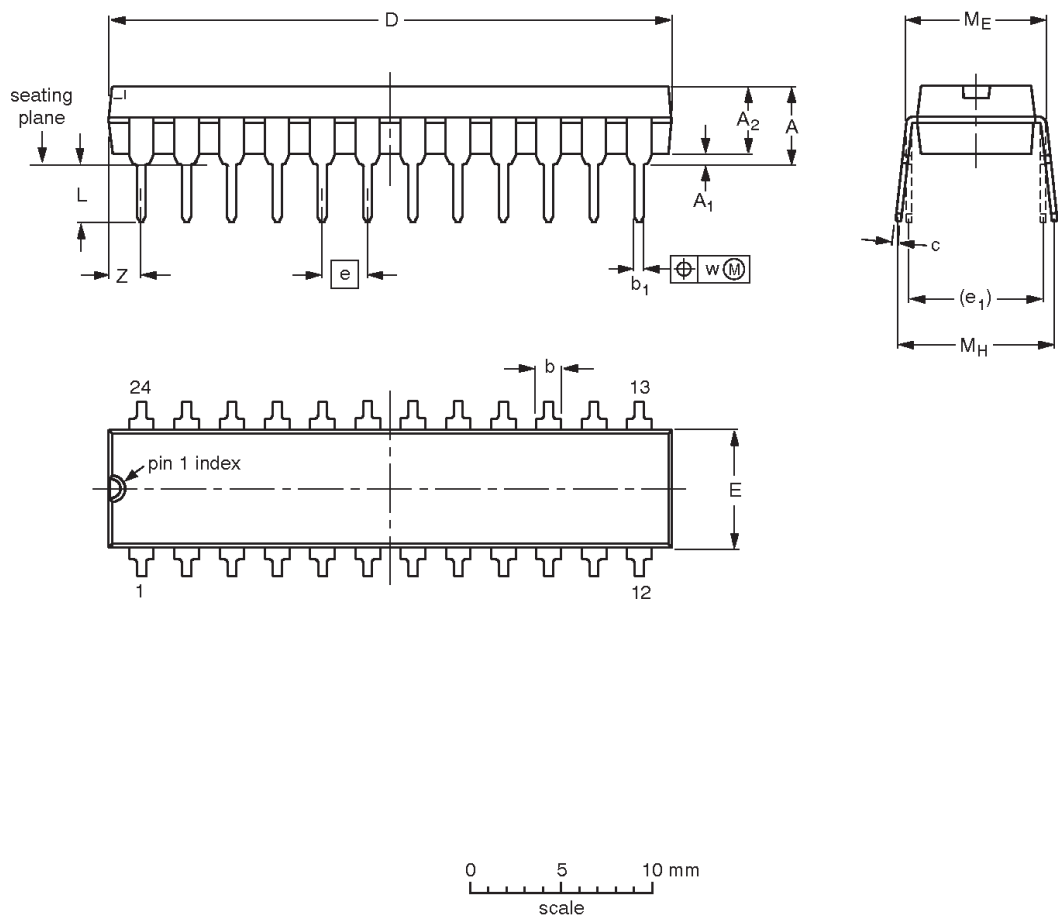
SF00128

10-bit buffer/line driver, non-inverting (3-State)

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DIP24: plastic dual in-line package; 24 leads (300 mil)

SOT222-1



DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.7	0.38	3.94	1.63 1.14	0.56 0.43	0.36 0.25	31.9 31.5	6.73 6.25	2.54	7.62	3.51 3.05	8.13 7.62	10.03 7.62	0.25	2.05
inches	0.185	0.015	0.155	0.064 0.045	0.022 0.017	0.014 0.010	1.256 1.240	0.265 0.246	0.1	0.3	0.138 0.120	0.32 0.30	0.395 0.300	0.01	0.081

Note
1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

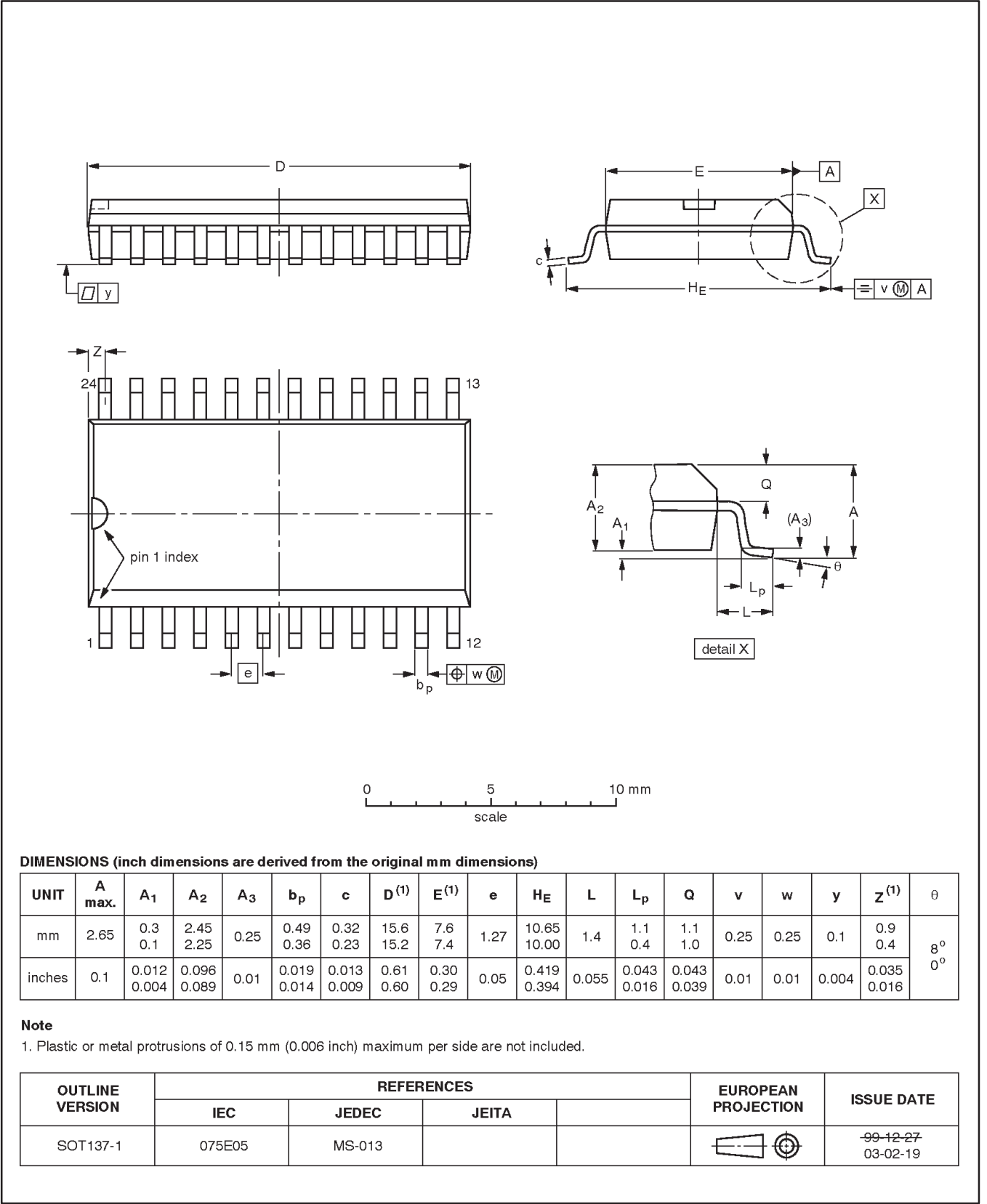
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT222-1		MS-001				99-12-27 03-03-12

10-bit buffer/line driver, non-inverting (3-State)

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SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1

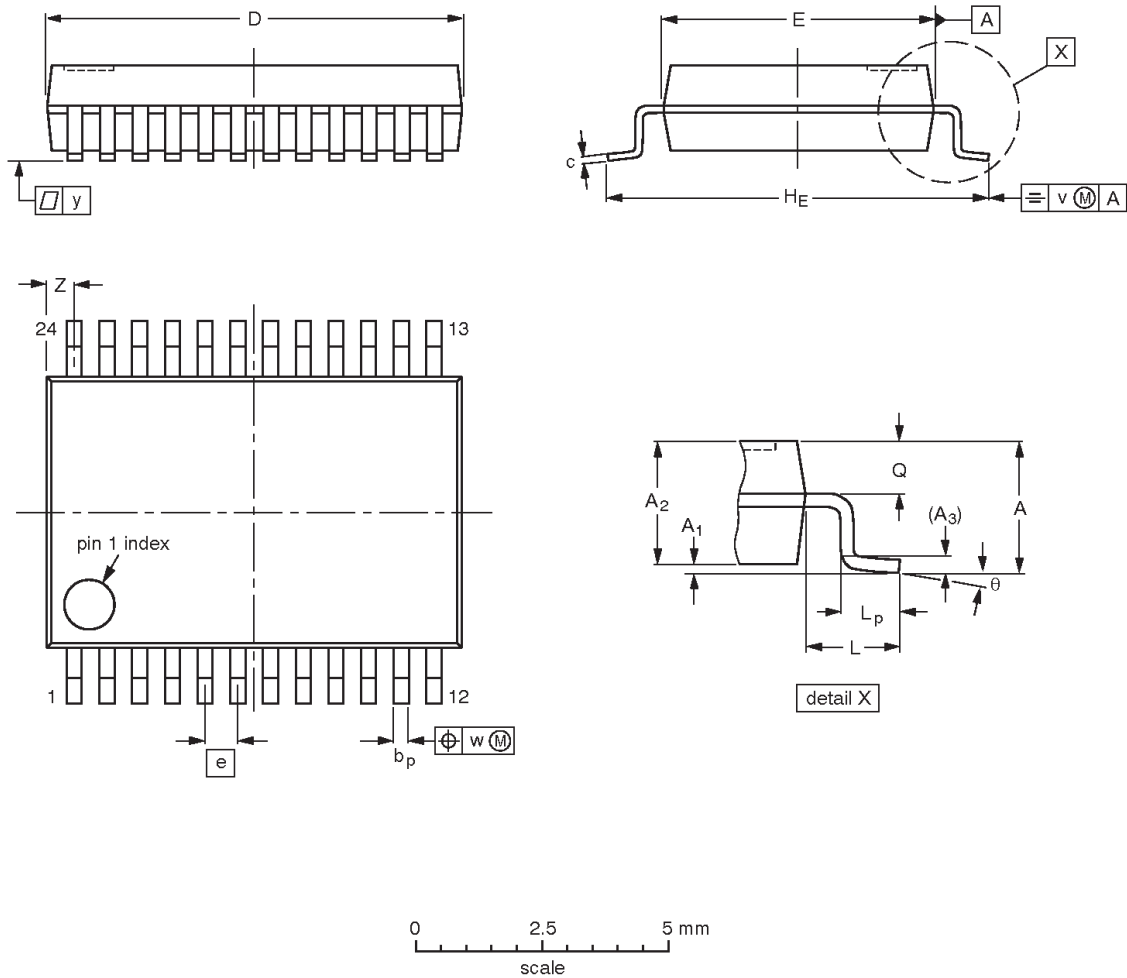


10-bit buffer/line driver, non-inverting (3-State)

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SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	8.4 8.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.8 0.4	8° 0°

Note
1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT340-1		MO-150				99-12-27 03-02-19

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REVISION HISTORY

Rev	Date	Description
_3	20040121	Product data (9397 750 12741). ECN 853-0880 A15336 of 21 January 2004. Replaces 74F827_74F828_2 dated 1994 Dec 5. Modifications: • Delete all references to 74F828 (product discontinued). • AC Characteristics table (for 10 outputs switching): change Limits columns' headings from $C_L = 50$ pF to $C_L = 300$ pF.
_2	19941205	Product specification. ECN 853-0880 14382 of 05 December 1994.

Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Date of release: 01-04

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Document order number: 9397 750 12741

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